

WHAT IS CLAIMED IS:

1. A method for cutting integrated circuit packages, comprising:
providing an integrated circuit package; and
cutting the integrated circuit package with a water jet.
2. The method of Claim 1, wherein cutting the integrated circuit package with a water jet comprises:
positioning the integrated circuit package adjacent a water jet;
pressurizing the water jet such that the water jet is operable to cut the integrated circuit package; and
cutting the integrated circuit package to a predetermined shape.
3. The method of Claim 1, wherein providing an integrated circuit package comprises providing a ball grid array package.
4. The method of Claim 1, wherein cutting the integrated circuit package with a water jet comprises cutting the integrated circuit package with a water jet having a plurality of abrasive particles.
5. The method of Claim 2, wherein pressurizing the water jet comprises pressurizing the water jet to a pressure between approximately 500 psi and approximately 2500 psi.
6. The method of Claim 1, wherein cutting the integrated circuit package with a water jet comprises cutting a plurality of integrated circuit packages by directing the water jet along at least one of a plurality of edges of the integrated circuit packages.
7. The method of Claim 1, wherein cutting the integrated circuit package with a water jet comprises cutting the integrated circuit package such that an interior portion of the integrated circuit package is accessible for testing.

8. A method for cutting integrated circuit packages, comprising:
providing an integrated circuit package;
positioning the integrated circuit package adjacent a water jet;
pressurizing the water jet such that the water jet is operable to cut the
integrated circuit package; and
cutting the integrated circuit package to a desired shape.

9. The method of Claim 8, wherein providing an integrated circuit
package comprises providing a ball grid array package.

10. The method of Claim 8, wherein cutting the integrated circuit package
to a desired shape comprises cutting the integrated circuit package with a water jet
having a plurality of abrasive particles.

11. The method of Claim 8, wherein pressurizing the water jet comprises
pressurizing the water jet to a pressure between approximately 500 psi and
approximately 2500 psi.

12. The method of Claim 8, wherein cutting the integrated circuit package
to a desired shape comprises cutting a plurality of integrated circuit packages by
directing the water jet along at least one of a plurality of edges of the integrated circuit
packages.

13. The method of Claim 8, wherein cutting the integrated circuit package
to a desired shape comprises cutting the integrated circuit package such that an
interior portion of the integrated circuit package is accessible for testing.

14. A system for cutting an integrated circuit package, comprising:
a computer operable to generate a predetermined cut pattern for the
integrated circuit; and
a water jet machining system operatively coupled to the computer and
operable to generate a water jet with a suitable pressure for cutting the
integrated circuit package into the predetermined cut pattern.

15. The system of Claim 14, wherein the water jet machining system
comprises:

a water supply;
an intensifier pump operatively coupled to the water supply and
operable to pump water through a conduit;
a hydraulic unit operatively coupled to the intensifier pump;
an attenuator operatively coupled to the water and operable to dampen
pressure fluctuations of the water in the conduit;
a valve coupled to the conduit and operable to control the flow of the
water; and
a nozzle coupled to conduit operable to direct the water along the
predetermined cut pattern.

16. The system of Claim 14, wherein the integrated circuit package is a
ball grid array package.

17. The system of Claim 14, wherein the water jet comprises a plurality of
abrasive particles.

18. The system of Claim 14, wherein the suitable pressure is between
approximately 500 psi and approximately 2500 psi.

19. The system of Claim 14, wherein the predetermined cut pattern comprises a plurality of edges of the integrated circuit package, wherein the integrated circuit package is formed on a polyimide strip.

5 20. The system of Claim 14, wherein the predetermined cut pattern comprises a pattern through an interior portion of the integrated circuit package such that the interior portion is accessible for testing.